

1SS355-BL

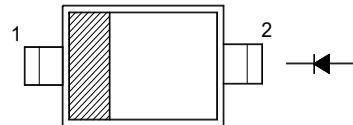
Silicon Epitaxial Planar Switching Diode

Features

- Small plastic package suitable for surface mounted design
- High reliability with high surge current handling capability

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Top View

Simplified outline SOD-323 (Bend Lead) and symbol

Applications

- High speed switching

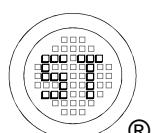
Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Value	Unit
Peak Reverse Voltage	V_{RM}	90	V
Reverse Voltage	V_R	80	V
Average Rectified Forward Current	$I_{F(AV)}$	100	mA
Peak Forward Current	I_{FM}	225	mA
Surge Forward Current (1 s)	I_{FSM}	500	mA
Power Dissipation	P_D	200	mW
Junction Temperature	T_j	150	°C
Storage Temperature Range	T_{stg}	- 55 to + 150	°C

Thermal Characteristics

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Ambient ¹⁾	$R_{\theta JA}$	625	°C/W

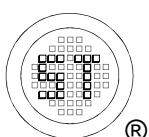
¹⁾ Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



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Electrical Characteristics ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Min.	Max.	Unit
Reverse Breakdown Voltage at $I_R = 100 \mu\text{A}$	$V_{(BR)R}$	80	-	V
Forward Voltage at $I_F = 100 \text{ mA}$	V_F	-	1.2	V
Reverse Current at $V_R = 80 \text{ V}$	I_R	-	100	nA
Capacitance between Terminals at $V_R = 0.5 \text{ V}$, $f = 1 \text{ MHz}$	C_T	-	3	pF
Reverse Recovery Time at $I_F = 10 \text{ mA}$, $I_{rr} = 0.1 \times I_R$, $V_R = 6 \text{ V}$, $R_L = 100 \Omega$	t_{rr}	-	4	ns



Electrical Characteristics Curves

Fig 1. Power Derating Curve

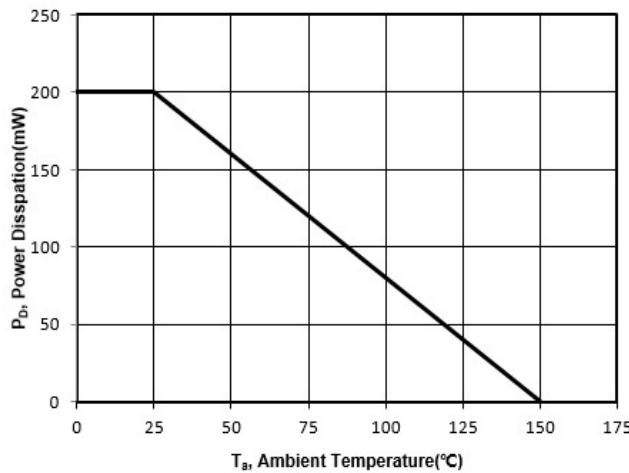


Fig 2. Total Capacitance vs. Reverse Voltage

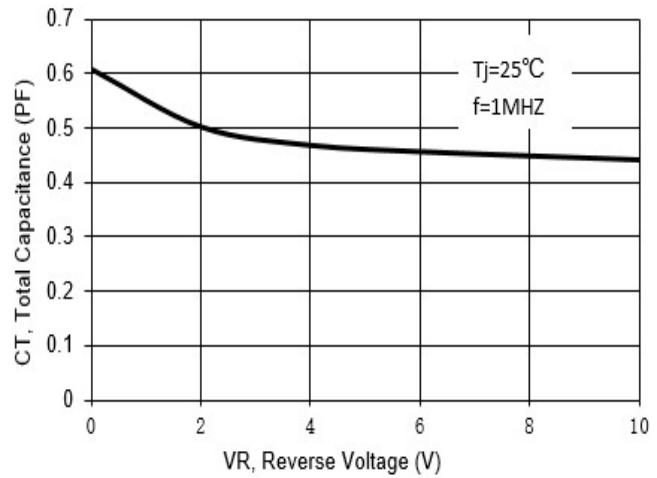


Fig 3. Reverse Current vs. Reverse Voltage

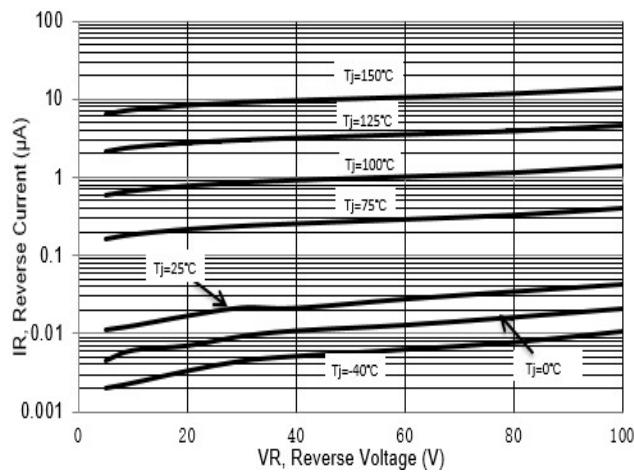
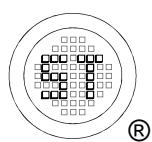
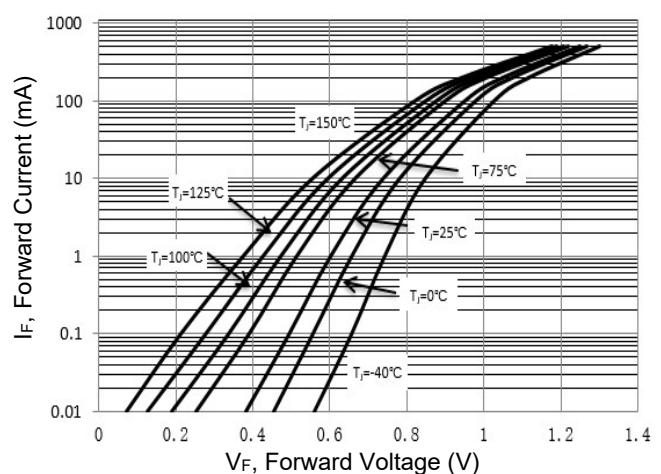


Fig 4. Forward Characteristics

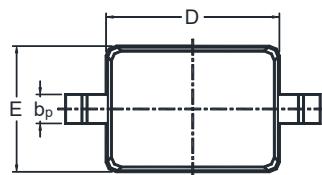
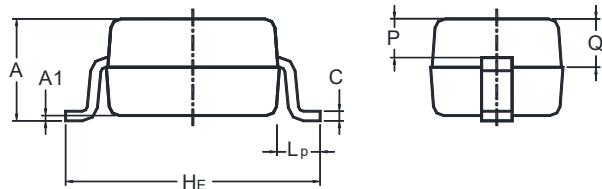


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PACKAGE OUTLINE

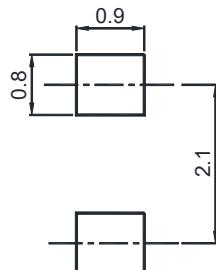
Plastic surface mounted package; 2 leads

SOD-323BL



UNIT	A	A ₁	b _p	C	D	E	H _E	L _p	Q	P
mm	1.1 0.8	0.1 0	0.4 0.25	0.18 0.09	1.8 1.6	1.35 1.15	2.8 2.3	0.5 0.1	0.5 0.3	0.4 0.3

Recommended Soldering Footprint



Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
SOD-323BL	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000

Marking information

"W2" = Part No.

"III" = Cathode line

Font type: Arial



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